



REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
		初版发行	2020-05-28			

适应基板厚度: 1.2mm~1.6mm
 温度范围: -25℃~85℃
 额定电压: 250V AC/DC
 额定电流: 1A
 绝缘电阻: ≥1000MΩ
 耐压: 800V AC/minute

15P	32.0	28.0	30.9
14P	30.0	26.0	28.9
13P	28.0	24.0	26.9
12P	26.0	22.0	24.9
11P	24.0	20.0	22.9
10P	22.0	18.0	20.9
9P	20.0	16.0	18.9
8P	18.0	14.0	16.9
7P	16.0	12.0	14.9
6P	14.0	10.0	12.9
5P	12.0	8.0	10.9
4P	10.0	6.0	8.9
3P	8.0	4.0	6.9
2P	6.0	2.0	4.9
NUMBER OF PINS	DIM A	DIM B	DIM C

2	PIN	n PCS	材质:铜合金,电镀:镀亮锡
1	Housing	1 PCS	材质:PA66 颜色:本色
NO.	NAME	Q'TY	DESCRIPTION

深圳市虹成电子有限公司

DRAW :		2020-05-28	TITLE:	HY2.0A WAFER DIP	HC-HY2.0-10A-M
DESIGN:		2020-05-28	SERIES:	HY2.0 SERIES	
CHECK:		2020-05-28	P/N:		DRAW NO.
APPROVED		2020-05-28	REV. 1.00	SCALE N/A	UNIT: mm
CUSTOMER DRAWING					SHEET: 1/1

技术要求:

- 1) 材质:见附表;
- 2) 电镀:见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;

4) 端子表面无氧化、电镀不良等现象。

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X.		X°	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	